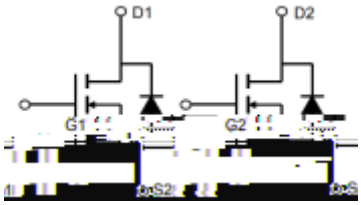
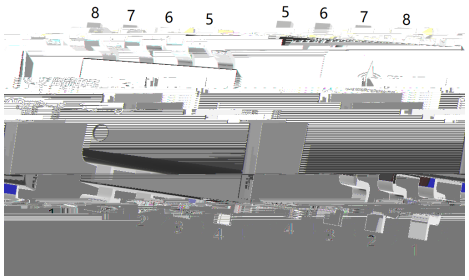
SOP-8 N MOS
Double N-CHANNEL MOSFET in a SOP-8 Plastic Package.

V_{DS}(V)=30V I_D=16.5A
$R_{DS(ON)}$@10V<7mΩ(Typ. 6.3mR)
$R_{DS(ON)}$@4.5V<12mΩ(Typ. 9.5mR)
Halogen-free Product.

MB/NB/UMPC/VGA , DC-DC ,
High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA, Networking DC-DC Power System,Load Switch.





PIN1 S1 PIN 2 G1 PIN 3 S2 PIN 4 G2
PIN 5 D2 PIN 6 D2 PIN 7 D1 PIN 8 D1

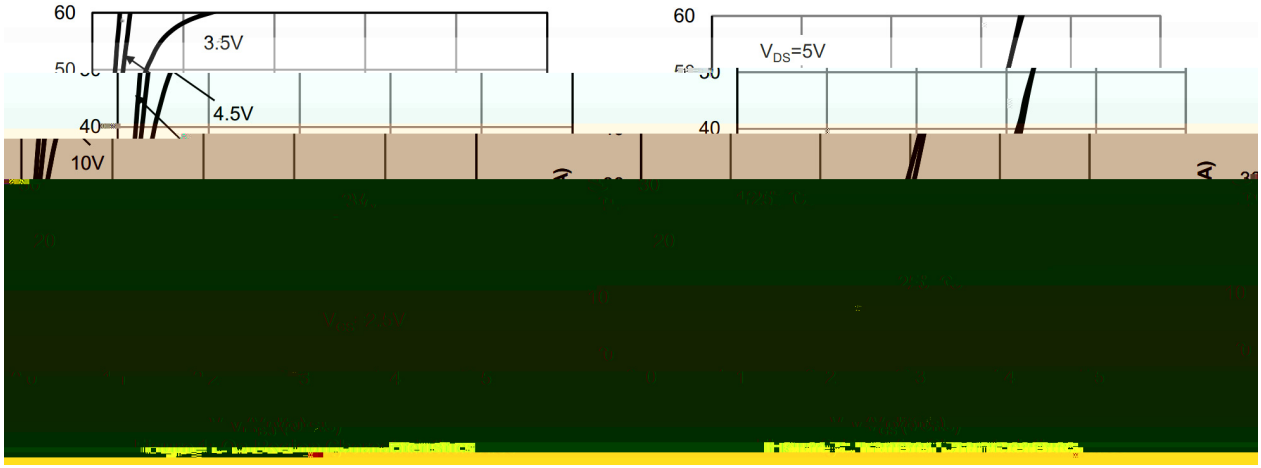
/ Marking

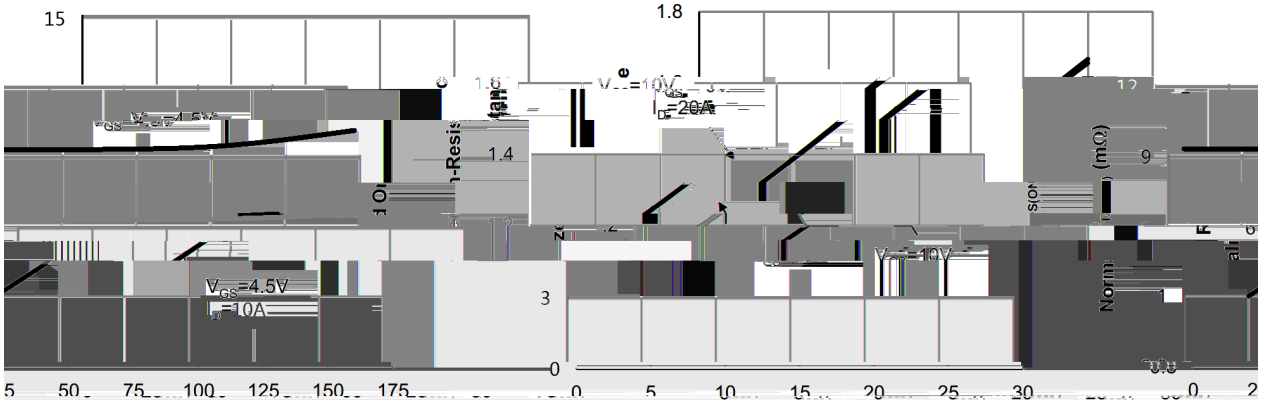
See Marking Instructions. ô — y

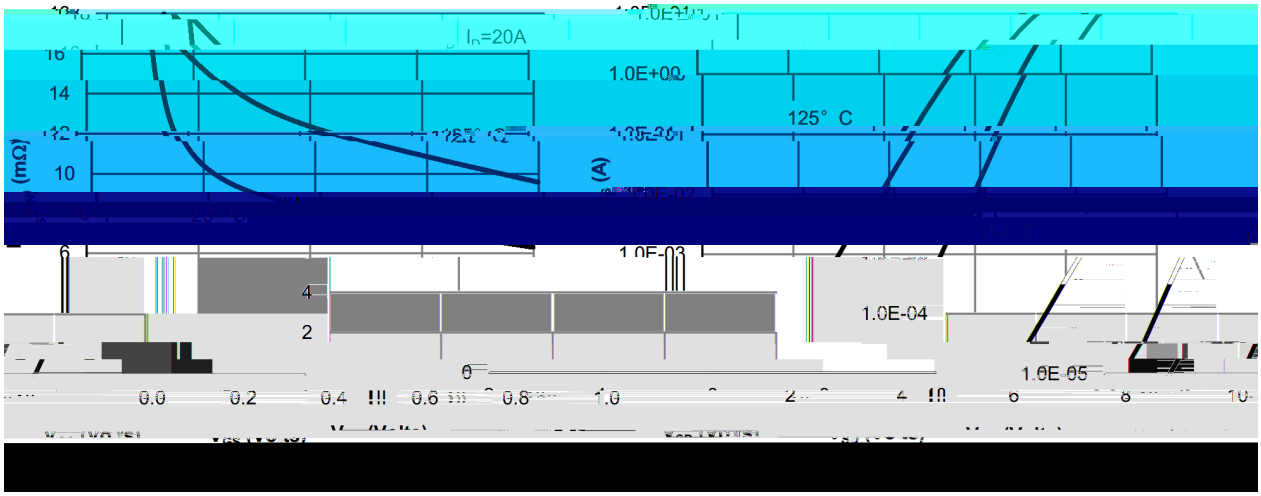
Parameter

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	V_{DS}=15 V V_{GS}=10V R_L=0.75Ω R_{GEN}=3Ω		11		ns
Turn-On Rise Time	t_r			14		ns
Turn-Off Delay Time	$t_{d(off)}$			38		ns
Turn-Off Fall Time	t_f			10		ns

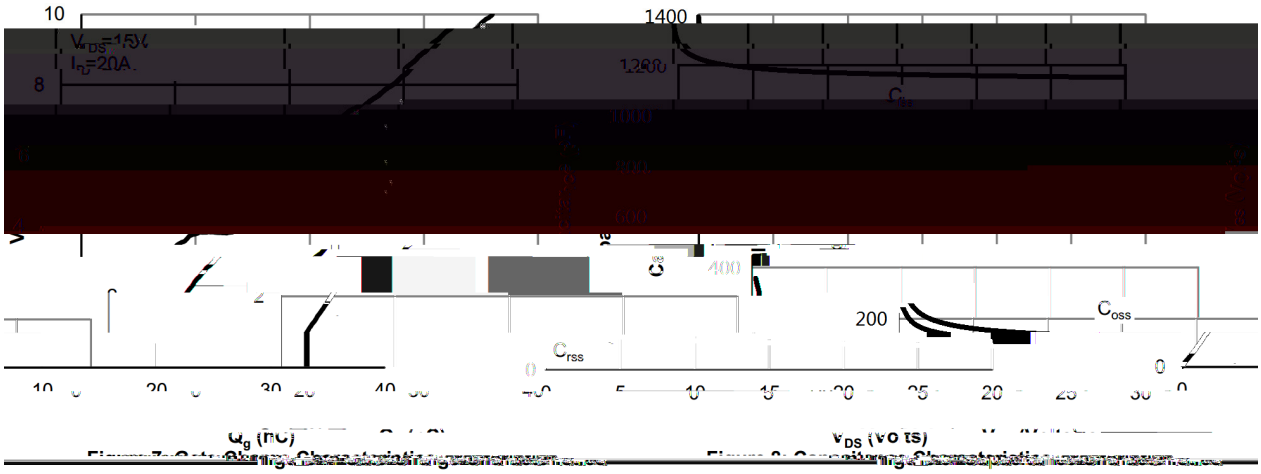
/ Electrical Characteristic Curve







/ Electrical Characteristic Curve



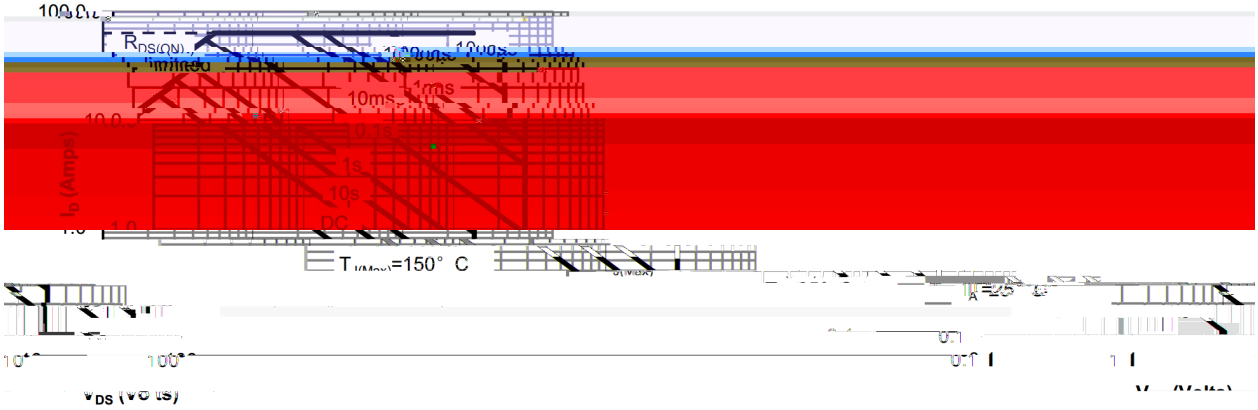


Figure 9: Maximum Forward Biased Safe Operating Area

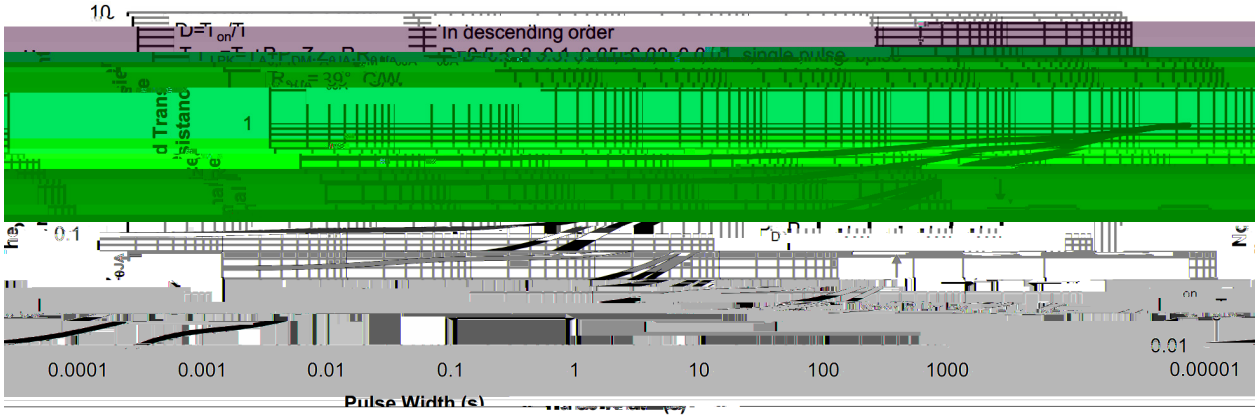
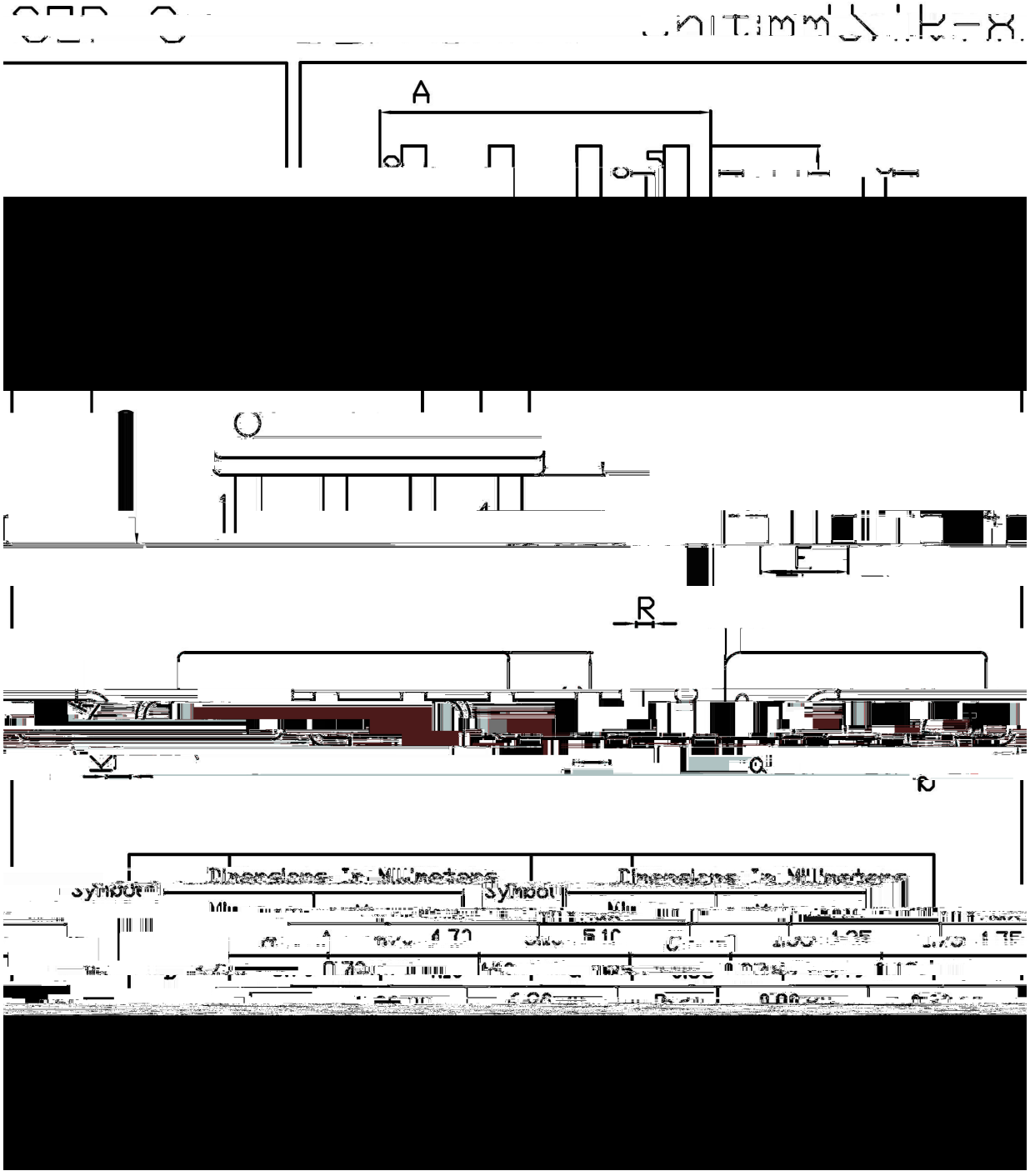
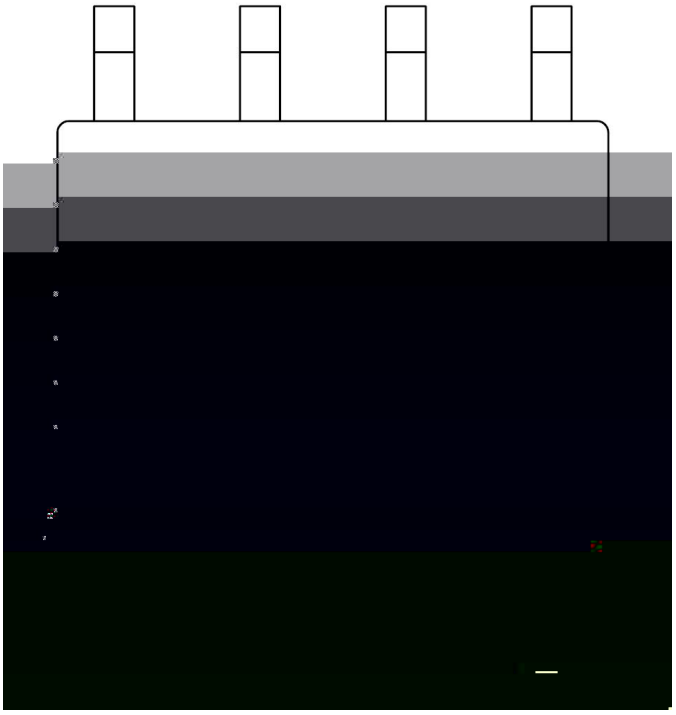


Figure 10: Normalized Maximum Transient Thermal Impedance

/ Package Dimensions



/ Marking Instructions



BR

070N03D

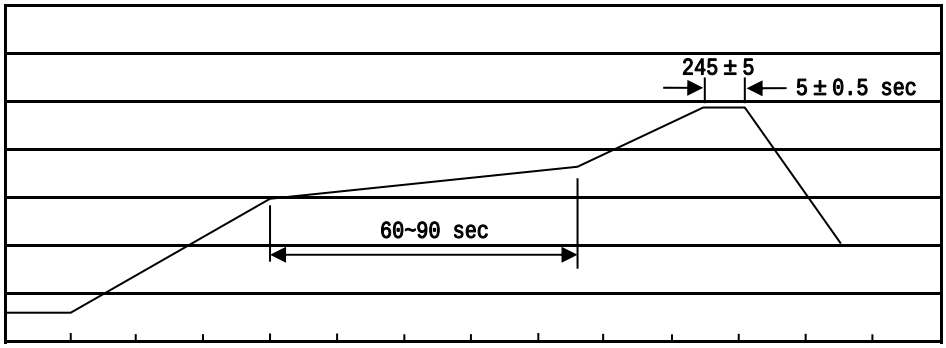
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Note:

BR: Company Code

070N03D: Product Type

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



			Note:
1	150 180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5	5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOP/ESOP-8	4,000	2	8,000	6	48,000	13 ×12	360×360×50	380×335×366

/ Notices